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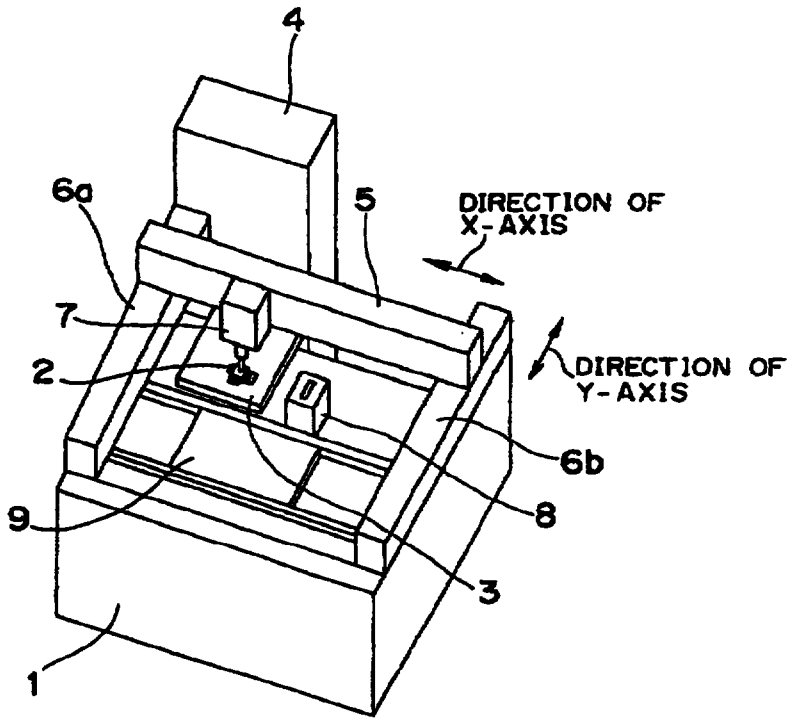
(54) Title: ELECTRONIC COMPONENT MOUNTING APPARATUS

(57) Abstract

The electronic component mounting apparatus includes: a tray feed section (4) for feeding an electronic component (2) to be placed; an x-axis robot (5) and a y-axis robot (6) for moving the electronic component (2) to be placed; a head section (7) for holding and moving the electronic component; a 3D sensor (8); and an image memory for storing height data as three-dimensional image data, thus enabling the positioning and the three-dimensional component configuration check of the electronic component (2) to be accomplished simultaneously in one process.